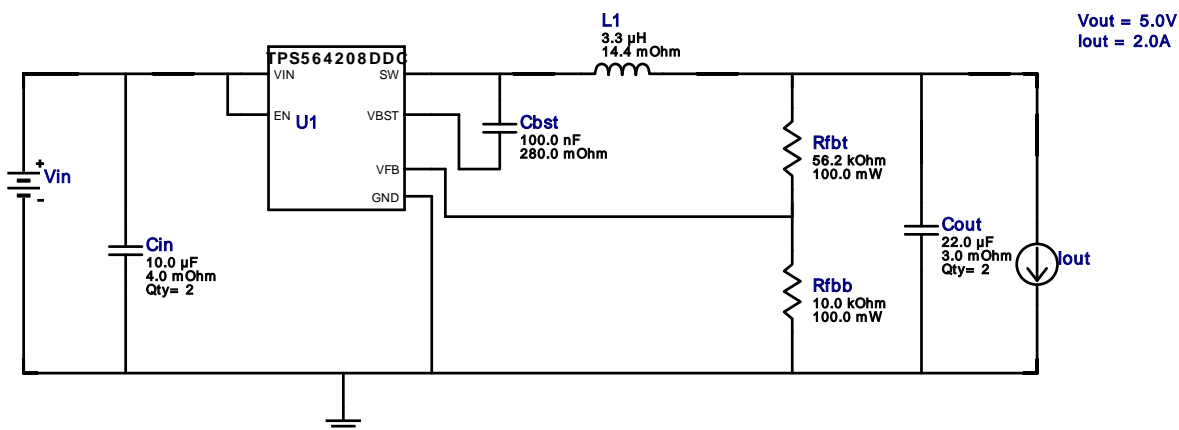


# WEBENCH® Design Report

Design : 1 TPS564208DDCR  
TPS564208DDCR 10V-12.6V to 5.00V @ 2A

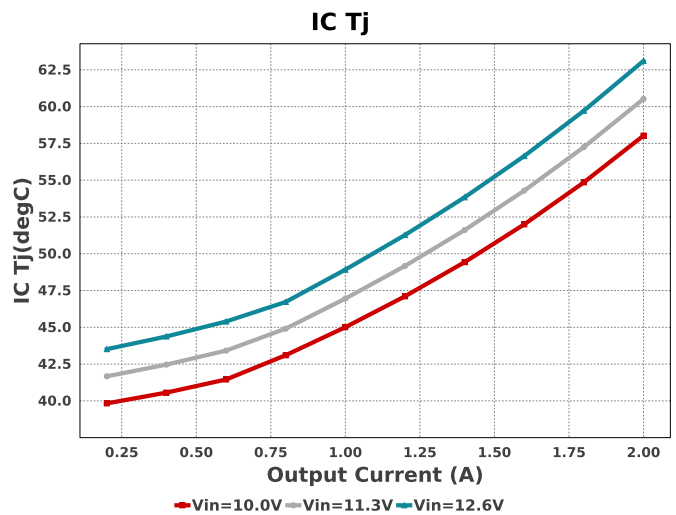
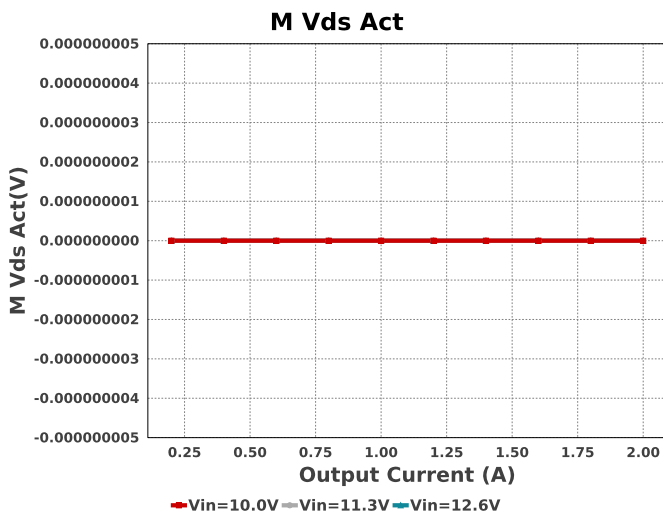
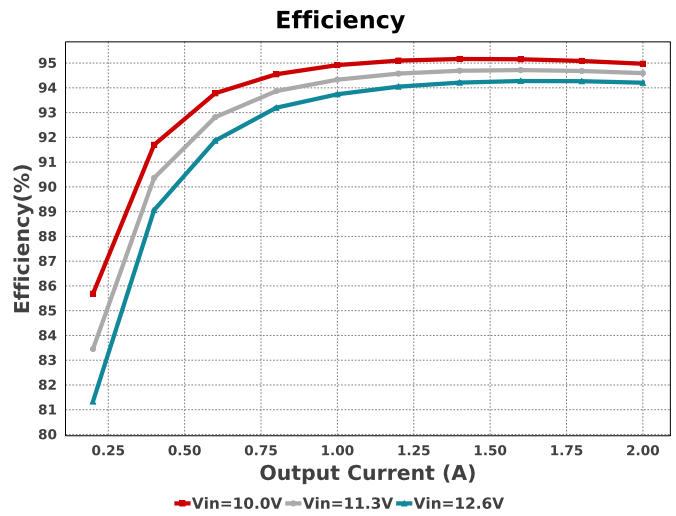
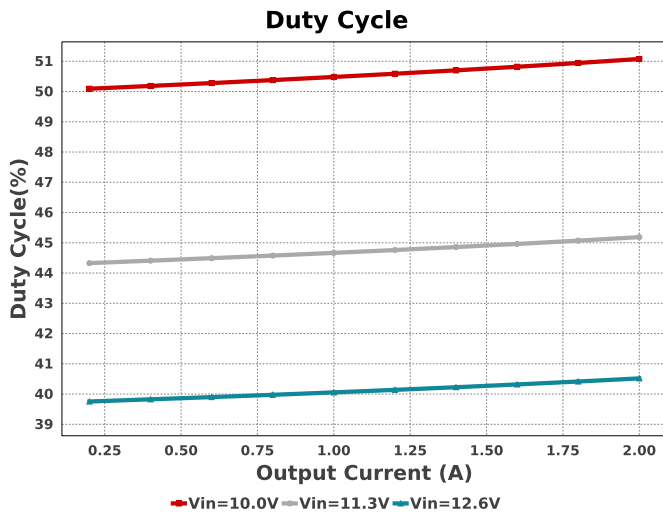
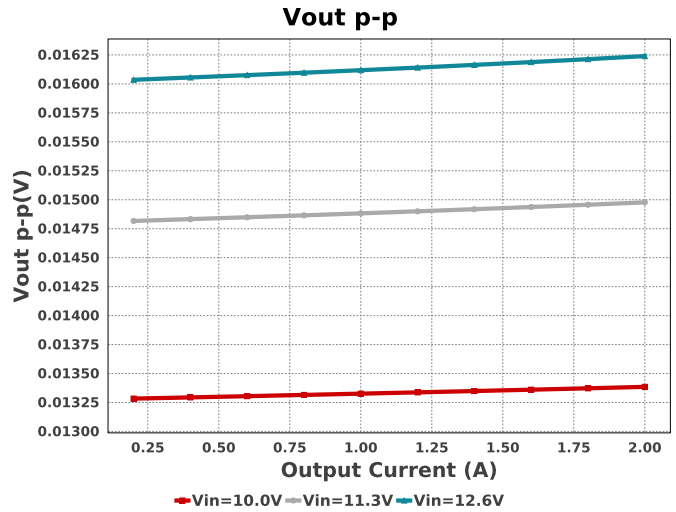
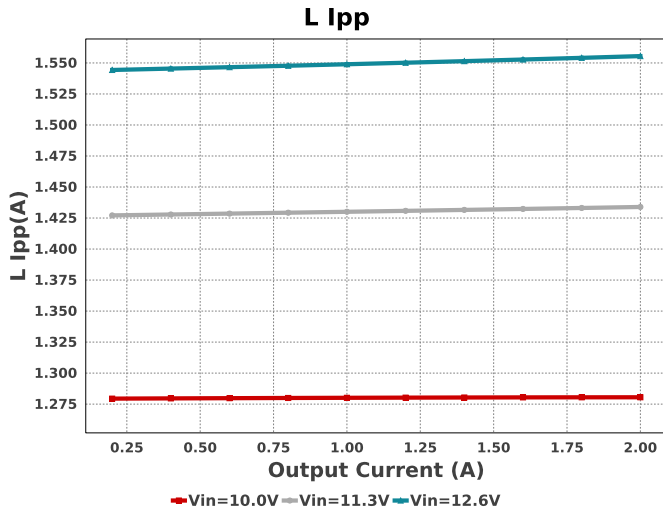
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VinMax = 12.6V  
Vout = 5.0V  
Iout = 2.0A

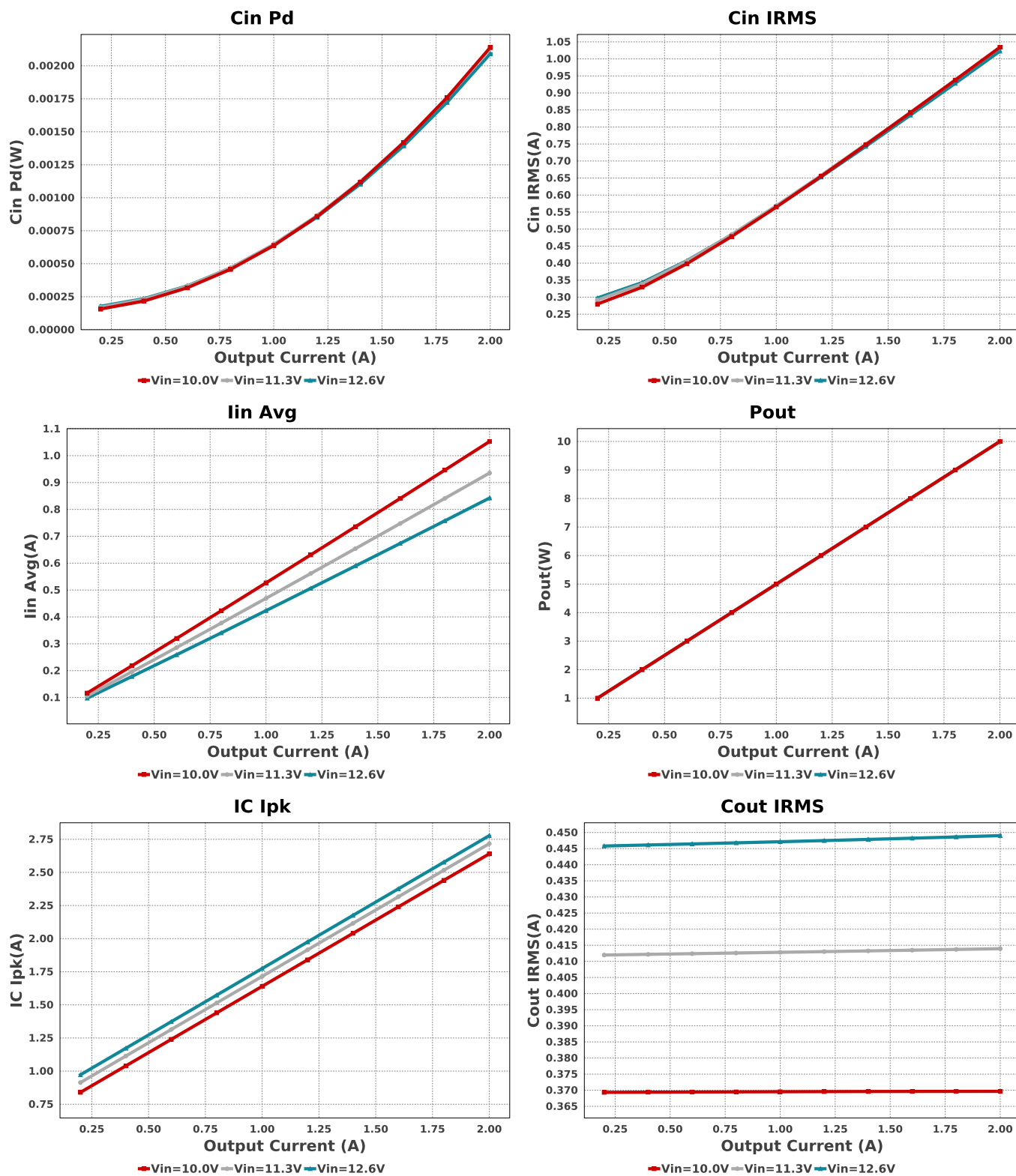
Device = TPS564208DDCR  
Topology = Buck  
Created = 2023-06-28 16:33:16.875  
BOM Cost = \$1.36  
BOM Count = 9  
Total Pd = 0.62W

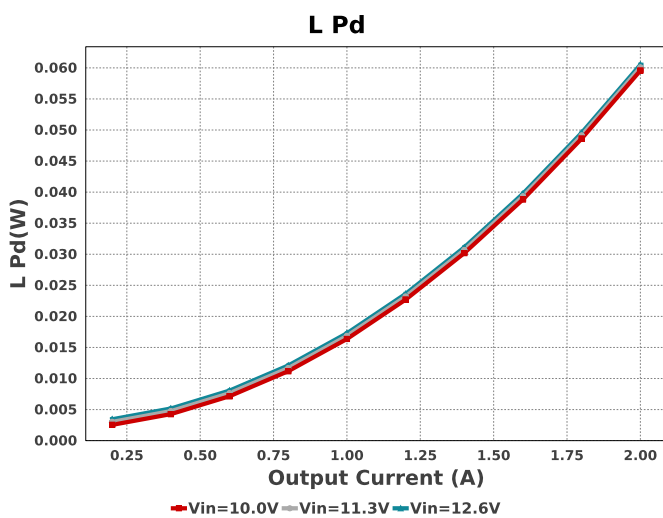
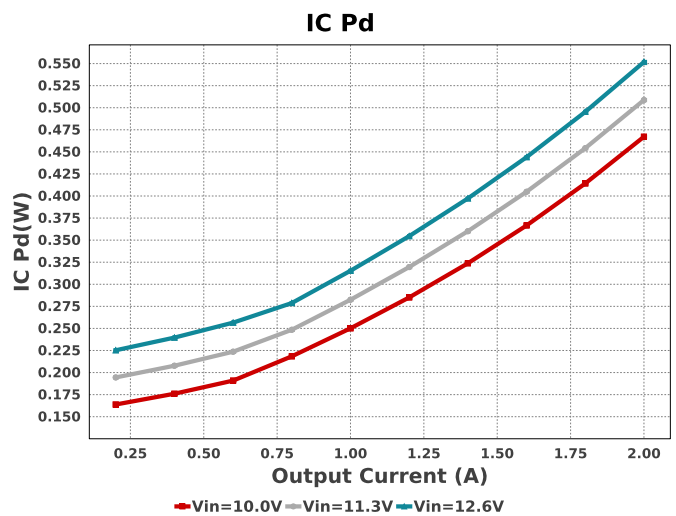
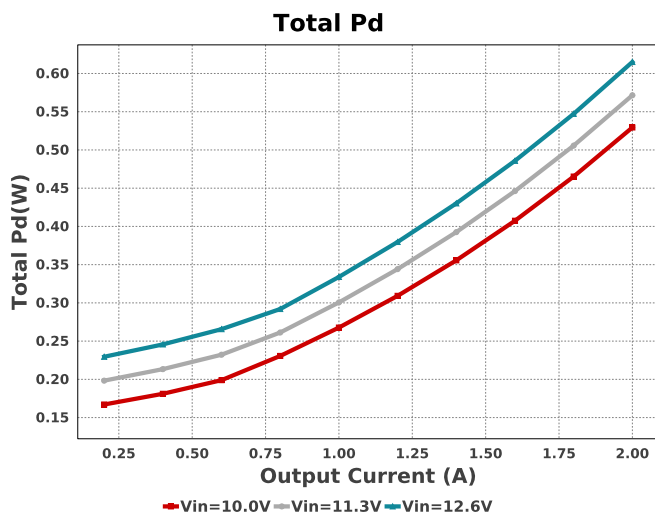
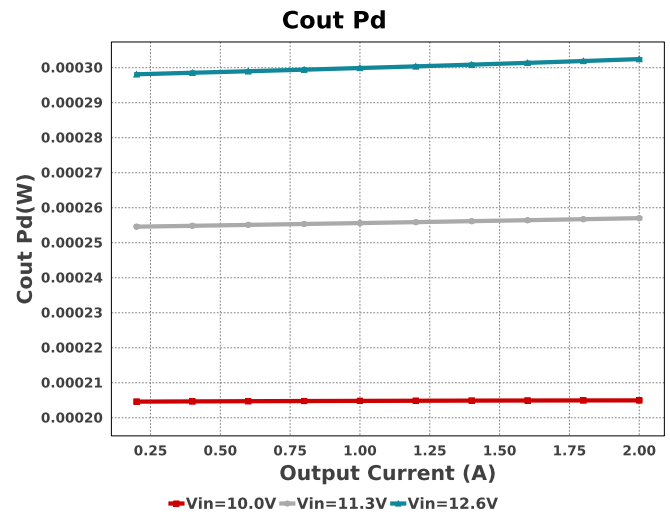
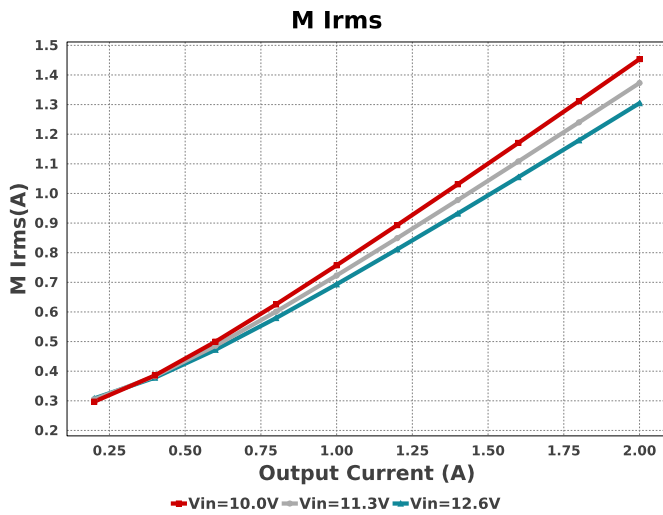


## Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbst	AVX	08053C104KAT2A Series= X7R	Cap= 100.0 nF ESR= 280.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.01	0805 7 mm <sup>2</sup>
Cin	MuRata	GRM21BR61E106MA73L Series= X5R	Cap= 10.0 uF ESR= 4.0 mOhm VDC= 25.0 V IRMS= 2.8 A	2	\$0.04	0805 7 mm <sup>2</sup>
Cout	MuRata	GRM21BR61A226ME44L Series= X5R	Cap= 22.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 3.84 A	2	\$0.09	0805 7 mm <sup>2</sup>
L1	Vishay-Dale	IHLP4040DZER3R3M01	L= 3.3 uH 14.4 mOhm	1	\$0.72	IHLP-4040DZ 166 mm <sup>2</sup>
Rfbb	Vishay-Dale	CRCW060310K0FKEA Series= CRCW...e3	Res= 10.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
Rfht	Vishay-Dale	CRCW060356K2FKEA Series= CRCW...e3	Res= 56.2 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
U1	Texas Instruments	TPS564208DDCR	Switcher	1	\$0.35	DDC0006A_N 10 mm <sup>2</sup>







## Operating Values

#	Name	Value	Category	Description
1.	BOM Count	9		Total Design BOM count
2.	Total BOM	\$1.362		Total BOM Cost
3.	Cin IRMS	1.023 A	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	2.092 mW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	449.04 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	302.46 $\mu$ W	Capacitor	Output capacitor power dissipation
7.	IC IpK	2.778 A	IC	Peak switch current in IC
8.	IC Pd	551.81 mW	IC	IC power dissipation
9.	IC Tj	63.109 degC	IC	IC junction temperature
10.	IC Tolerance	15.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA	60.0 degC/W	IC	IC junction-to-ambient thermal resistance

#	Name	Value	Category	Description
12.	Iin Avg	842.47 mA	IC	Average input current
13.	L Ipp	1.556 A	Inductor	Peak-to-peak inductor ripple current
14.	L Pd	60.504 mW	Inductor	Inductor power dissipation
15.	M1 Irms	1.305 A	Mosfet	Q lavg
16.	M Vds Act	0.0 V	Mosfet	Voltage drop across the MosFET
17.	Cin Pd	2.092 mW	Power	Input capacitor power dissipation
18.	Cout Pd	302.46 $\mu$ W	Power	Output capacitor power dissipation
19.	IC Pd	551.81 mW	Power	IC power dissipation
20.	L Pd	60.504 mW	Power	Inductor power dissipation
21.	Total Pd	615.04 mW	Power	Total Power Dissipation
22.	Duty Cycle	40.518 %	System	Duty cycle
23.	Efficiency	94.206 %	Information	Steady state efficiency
			System	
24.	FootPrint	220.0 mm <sup>2</sup>	Information	Total Foot Print Area of BOM components
			System	
25.	Frequency	588.619 kHz	Information	Switching frequency
			System	
26.	Iout	2.0 A	Information	Iout operating point
			System	
27.	Mode	CCM	Information	Conduction Mode
			System	
28.	Pout	10.0 W	Information	Total output power
			System	
29.	Vin	12.6 V	Information	Vin operating point
			System	
30.	Vout	5.0 V	Information	Operational Output Voltage
			System	
31.	Vout Actual	5.031 V	Information	Vout Actual calculated based on selected voltage divider resistors
			System	
32.	Vout Tolerance	3.723 %	Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
			System	
33.	Vout p-p	16.24 mV	Information	Peak-to-peak output ripple voltage
			System	

## Design Inputs

Name	Value	Description
Iout	2.0	Maximum Output Current
VinMax	12.6	Maximum input voltage
VinMin	10.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	TPS564208	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 10.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### Design Assistance

1. Master key : C3647A6DE7DCF59A0EE9E8B66B879D[v1]
2. **TPS564208** Product Folder : <http://www.ti.com/product/TPS564208> : contains the data sheet and other resources.

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